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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Adae-Amoakoh *et al.*

Examiner: Andujar, Leonardo

Serial No.: 09/827,014

Art Unit: 2826

Filed: 4/5/01

For: **ECONOMICAL HIGH DENSITY CHIP CARRIER****FAX RECEIVED**Commissioner for Patents
Washington, D.C. 20231

APR 07 2003

TECHNOLOGY CENTER 2800

Sir:

This paper is being filed in response to a Final Office Action dated February 26, 2003 in connection with the above-identified application. Reconsideration and allowance are respectfully requested in view of the Amendments and Remarks below.

Amendment**In the Claims:**

Claims 1-6, 9 and 20 have been amended prior to the present office action response. No claims are amended herein in the present office action response. Currently pending claims 1-9 and 20 for consideration by the Examiner are as follows:

1. (PREVIOUSLY AMENDED) An electronic structure comprising:

a substrate having a dielectric layer between a first metal layer and a second metal layer, the second metal layer being disposed above the first metal layer, the first metal layer having a

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CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)				Docket No. END920000149US1
Applicant(s): Adae-Amoakoh et al.				
Serial No. 09/827,014	Filing Date 4/5/2001	Examiner Andujar, Leonardo	Group Art Unit 2826	
Invention: ECONOMICAL HIGH DENSITY CHIP CARRIER				
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I hereby certify that this <u>Amendment (8 pages- last page Appendix A)</u> (Identify type of correspondence)				
is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. <u>703-308-7722</u>)				
on <u>4/7/2003</u> (Date)				
<u>Kim Dwileski</u> (Typed or Printed Name of Person Signing Certificate)  (Signature)				
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